



The DAQ Upgrade II at LHCb

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Plan

- LHCb, LHCb Upgrade I and II
- Genesis of the DAQ project at IN2P3
 - Online system for the LHCb detector
 - Online evolution to LHCb Upgrade I
 - Planned evolution toward LHCb Upgrade II
- The DAQ project for LHCb Upgrade II at IN2P3
- Conclusions

LHCb, LHCb Upgrade I and II

	Date	Runs	Instantané $\mathcal L$ [cm ⁻² s ⁻¹]	Intégré £ [fb⁻¹]	<i>pp</i> interactions per collision
LHCb	2010 – 2018	Run 1 & 2	4 × 10 ³²	9	1
LHCb Upgrade I	2022 – 2033	Run 3 & 4	2 × 10 ³³	50	5
LHCb Upgrade II	2036 – 2041	Run 5	1.5 × 10 ³⁴	300	40

Online system for LHCb (2010-2018)

Online overview for the LHCb detector

- The online system consist of three main components:
 - Data Acquisition (DAQ)
 - Timing and Fast Control (TFC)
 - Experiment Control System (ECS)

Upstream of the DAQ, the Level-0 trigger reduces the collision rate from 40 MHz down to 1 MHz



- The DAQ is connected to the front-end electronics via 6000 optical links using the GOL protocol at 1.6 Gbits/s and analogue transmission for the VELO
 - Event building is performed using a common readout card (TELL1) and a Gigabit Ethernet network.
 - For each triggered bunch-crossings, the event builder collects all the fragments, assembles them and distributes the event to the HLT farm.

The bandwidth of the DAQ is 0.45 Tbits/s

TFC overview for the LHCb detector

The TFC system drives all stages of the data readout of the LHCb detector between the front-end electronics and online processing.

The TFC distributes the beam-synchronous clock, the L0 trigger, synchronous resets and fast control commands.

The TFC relies entirely on CERN custom VME cards (TTCex, TTCtx) and ship sets (TTCrx, QPLL) which disctribute the LHC clock wiht a jitter of 10 ps and a phase determinism of 100 ps





The Level-0 trigger of the LHCb detector

- The Level-0 trigger (L0) reduces the LHC bunch crossing rate of 40 MHz to the rate of 1 MHz with which the entire detector can be read out.
- Due to their large mass, the signature of a *b*-decay is a displaced vertex with particles of large transverse momentum (pT) or energy (ET).
- Threfore, the Level-0 trigger attempts to reconstruct:
 - the highest ET hadron, electron and photon clusters in the calorimeters,
 - the two highest pT muons in the muon chambers.
- A Level-0 Decision Unit collects all the information and derives the final Level-0 trigger decision for each bunch crossing.



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CPPM

Focus on the Level-0 Muon custom processor

The L0 muon processor reconstructs track segments in the muon detector and measures their transverse momentum
Cavern
Barrack

Level-0 Muon

FPGA: Stratix GX Optical I/O: 1864 @ 1.6 Gbit/s Bandwidth: 2.7 Tbits/s Processing time: 1.2 μs Form Factor: 9U: 400x220 mm



48 Processing boards





in the cavern

IN2P3 contributions to the Level-0

The IN2P3 Institutes were the main contributors to the Level-0 trigger

Component	Institute			
L0 Pile up	NIKEF			
L0 Calorimeter	IN2P3-LAL			
L0 Muon	IN2P3-CPPM			
L0 Decision Unit	IN2P3-LPC			
Project Leader	IN2P3-CPPM			

With the removal of the Level-0 trigger in the LHCb Upgrade I, the CPPM migrated to the design, production and maintenance of the generic and multi-purpose readcout card called PCIe40

Online evolution to LHCb Upgrade I (2022 – 2033)

Increasing the instantaneous luminosity

- The Level-0 trigger rate staturates for hadronic final states at the luminosity of Run 1 and 2 (4x10³² cm⁻²s⁻¹)
- High rate of beauty and charm decay at 2x10³³ cm⁻²s⁻¹



- In order to efficiently select a large number of interesting *b* and *c*-decays, the optimal approach is to:
 - remove the level-0 trigger
 - move to a new paradigm where all bunchcrossings are assembled, reconstructed with ultimate precision and then event selected in near real time.
- Selection efficiency increases between 2 and 3





(b) TOS efficiencies in $B^0 \to D^- (K^+ \pi^- \pi^-) \pi^+$.

DAQ architecture for the LHCb Upgrade I – Run 3

- The DAQ uses standard protocol and COTS components as far as possible :
 - PCi Express, Infiniband network
 - PC-server designed for up to 8 GPUs
 - DMA transfert
- The DAQ is connected to the front-end electronics via 11 000 optical links using the GBT protocol at 4.8 Gbits/s
- The first stage is a PC-server housing 3 readout cards, PCIe40 and 3 GPUs for HLT1
- Event building is performed for each bunch-crossing using a 200 Gigabit Infiniband network.



A trigger-free architecture with 40 Tbits/s of total bandwidth

Generic and multi-purpose PCIe40 card

LHCb has chosen to use a single, custombuilt card for data acquisition, TFC and slow control: the PCie40 card

 1250 cards were produced between June 2019 and May 2020 for the LHCb, ALICE, Mu3e and Belle II collaborations

Built around the Arria10 FPGA, the different functionalities are achieved by loading a variety of gatewares onto the FPGA



PCle40
FPGA
Family: Arria 10
Logic Elements: 1 150 kLE
Max frequency: 644 MHz
RAM: 53 Mb
Optical I/O
bidirectional links 10 Gbps: up to 48 Gbps
TFC PON: 2
CPU I/O
PCIe GEN3: 16
Output bandwidth: 100 Gbps
Form Factor
PCIe: 241 x 111 mm

CPPM

User gateware and continous integration



User gateware dedicated to triggerless DAQ faces significant challenges:

- data frames arrive asynchronously over all optical links
- data frames need to be decoded, realigned according to their BXID, assembled into an event packet. Event packets will then be sent to the DAQ network.
- Aggregated data can also be manipulated into primitive such as local clusters.
- A framework has been introduced in which blocks common to all subdetectors (blue) are developed centrally. This allows subdetector developers to focus only on specific blocks (red) for their system.
- The online system required 21 gatewares. These are built, verified and versioned using the GitLab's Continuous integration tools



TFC architecture for the LHCb Upgrade I – Run 3

- The TFC relies entirely on the PCIe40 card. It is a complex architecture with multiple hubs
- The PCIe40's clock tree uses highprecision PLLs to ensure good jitter of the bunch clock recovered at the frontend electronics.
- The phase between the bunch clock recovered at the front electronics and the bunch crossing must remain the same after a reset or a power cycle.
 - This is known as *phase determinism*.
 - It is lost in FPGA transceivers.
 - A complex mechanism has been implemented in the FPGA Arria 10 to achieve an accuracy of 200 ps.
 - Mechanism depends on Vendor and FPGA familly



Planned evolution towards LHCb Upgrade II

DAQ relevant enhancements to LS3



For Run 4, the RICH detector will deploy a new front-end electronics during LS3 :

- New FE ASIC with timing measurement capabilities O(25 ps)
- Optical link protocol lpGBT instead of GBT
- Increase the output bandwidth by ~30 %
- Phase determinism at the level of O(50 ps) matching the MAPMT jitter of 150 ps
- The RTA will experiment with a custom DWT processor. It reconstructs trace segments in the SciFi using retina architecture that requires a network of powerful FPGAs.

Generic and multi-purpose card PCIe400

PCIe400						
FPGA						
Family: Agilex 7M						
Logic Elements: 3 851 kLE						
Max frequency: 1 GHz						
RAM: 311 Mb						
HBM: 32 GB						
ARM Cortex processor: 4 core						
Optical I/O						
bidirectional links 25 Gbps: up to 48						
bidirectional links 112 Gbps: up to 4						
TFC PON or White Rabbit: 2						
CPU I/O						
PCIe GEN5: 16						
Output bandwidth: 400 Gbps						
Timing						
high precision PLL with jitter < 100 fs						
White Rabbit node						
Form Factor						
PCIe: 268 x 111 mm						

exploratory features





First prototype – January 2025

Intersested collaborations: Belle II, ...

DAQ architecture for the LHCb Upgrade I – Run 4

- The architecture of the DAQ system remains unchanged with respect to the Run 3.
- ► However, due to the limited length of the lpGBT connections (≤ 150 m), the DAQ must be extended, in the cavern not at the surface.



TFC architecture for the LHCb Upgrade I – Run 4

- The TFC architecture has to evolve:
 - New protocol to receive the bunch clock, White Rabbit (**)
 - Improved phase determinism from ~200 ps down to ~50 ps
 - Experience PCIe400 phase determinism at ~10 ps



(**) Expertise at IJCLab

Toward the Online for Upgrade II

- egend White Rabbi Fast Control PCIe40 card PCIe400 card Fiber going to IT4 Fiber going to IT3 Fiber(s) going 9.6 Gb WR switch 1v6 Partition Partition Paidor 12 Readout Board Board Board Board Tell400) in IT3 From FE From FE 10 Gb/s To FE *can be PCIe400 Undeground Surface UX85B Data Center
- A trigger-free architecture with a total bandwidth of 200 Tbits/s is under discussion for Upgrade II
- Many unkowns:
 - evolution of the computing market, form factor of GPU, PC-server, etc
 - roadmap for the future generation of FPGA,
 - processing power required to prepare the sub-detector's raw data for HLT.
- The collaboration setup a small group of experts who are estimating the processing power required in the back-end and studying the optimum data acquisition system from the front-end electronics up to the HLT1 decoding.
 - It will have to make recommendations in 2026 in order to outline the DAQ architecture in the *TDR Data Processing Framework* by the end of 2026
- Specifications of the multi-purpose card for the Upgrade II in 2027

The DAQ project for LHCb Upgrade II at IN2P3...

LHCb Data Acquisition Enhancement TDR

- The LHCb collaboration submit to the LHCC, the LHCb Data Acquisition Enhancement Technical Design Report describing the evolution of the DAQ for Run 4 :
 - New PCIe400 readout card for RICH channel expansion
 - Implement an hardware processor based on the RETINA architecture and PCIe400 boards to perform real-time track reconstruction in SciFi
 - Learn how to deploy, step by step, a clock targeting an ultimate jitter and phase determinism of O(10 ps)
- The LHCC notes that these development represents an important and effective step towards the future Upgrade II and recommends approval to allow resources to become available and MoUs to be signed.
- Approved by the CERN Research Board in December 2024

Proto-project PCIe400 at IN2P3

- We propose to IN2P3 a proto-project in the continuity of the PCIe400 R&D
- Mid-September 2024, the IN2P3 reviewed the proto-project in order to assess its maturity and whether IN2P3 has the resources to commit with confidence



Premiminary recommendations:

- Identified as IN2P3 flagship project with high stakes and commitment
- Extend the R&D phase until the end of 2025 to allow time for the project to mature and overcome key technological barriers

Organisation of the proto-project PCIe400 – LS3

- Supported by 5 IN2P3 institutes: CPPM, IJCLab, LAPP, LPNHE, SUBATECH as well as by the LHCb / Online team
 - WP1 Hardware: the design and production of the boards as well as preparatory work for the LS4 version
 - WP2 Gateware:
 implementation of the framework and the continuous integration of the gatewares
 + specific developments
 - WP3 Software:

software development and a series of tests for the qualification and production of the PCIe400 cards

WP4 Time distribution / system integration:
 LHCb testing and qualification



Coordinators for each WP are idendified as well as the *Technical and Physics Coordinators*

Contributors LS3 – from KDP2 review Sept 2024

Physicists and engineers from IN2P3

Nom des personnes	Statut
СРРМ	
Renaud LE GAC	DRCE
Nom des personnes	Statut
СРРМ	
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Jean-Luc MEUNIER	IR
Stefano RUSSO	IR
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Christophe RENARD	IR
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From others institutes

Nom des personnes	Statut				
CERN					
Paolo DURANTE	IR				
TBD	Etudiant				
TBD	IR				
TOTAL (FTE)					

Master plan

	Run	3	LS3				Run 4					LS4		
	2025	2026	6 20)27	20	28	2029	2030	2031	2032	2 20	33	2034	2035
PCle400	Proto. Debug & Qualif.	Produ prepa	uction ration	Pr	od.	Sut Corr	o-detector missioning		· · · ·					
Upgrade II	Spec.			De	sign	Debug & Qualif.	Productic Preparati	on on	Prod.	Sub Com	o-detector missioning			

- A card of similar complexity to the PCIe400 was assumed for the Upgrade II timeline.
- Decision on the Upgrade II version should be taken by end 2026. They are several possibilities:
 - Only PCIe400
 - PCIe400 + Concentrator on top of it
 - Mixture of PCIe400 and Upgrade II version
 - Only Upgrade II version
 - New idea which can appear in the future

Deliverables – LS3

New date taking into account the update of LHC schedule

Date	Deliverable
December 2026	Performance reports on LpGBT and phase determinism
July 2028	Delivery of a hundred PCIe400 cards to the LHCb Online team with Low Level gateware and software

	PCIe400	100
RICH	55	024-(
DWT axial	64	CC-2(
DWT stereo	32	-LHC
Total	151 + Spares	CERN

Deliverables – LS4

Sub-detector	DAQ links	Total	Average bandwidth
		bandwidth in Tbit/s	per lpGBT link in Gbit/s
VELO	3 400	34	10.0
UP	1 888	7	3.7
Magnet Station	1 400	5	3.6
Mighty Tracker	9 500	30	3.2
RICH	5 700	30	5.3
TORCH	4 312	27	6.3
PicoCal	2 360	21	8.9
MUON	1 576	16	10.2
Total	30 136	170	

Table 5: Number of LpGBT links and their occupancies for LHCb Upgrade II 3

- The number of boards to be produced for the Upgrade II system can be estimated from the number of lpGBT links, as they all need to be connected to a board.
 - The total is $\mathcal{O}(750)$ modules without spares
 - This is comparable to the number of PCIe40 cards produced for LHCb Upgrade I
- The delivery date is under discussion. It will depend on the needs of the sub-detectors to build and commission their system, most likely in the '30s.

Person-power needed

Fields of interest per institute:

Work Packages	Institutes
WP1 Hardware	CPPM, LHCb/Online
WP2 Gateware	CPPM, LAPP
WP3 Software	CPPM, SUBATECH, LHCb/Online
WP4 Timing distribution techniques	CPPM, IJCLab, LPNHE, LHCb/Online

Required person-power for the PCIe400 version:

	Lon				
Work Package	2025	2026	2027	2028	Total (FTE)
Management	0.7	0.4	0.3	0.3	1.7
Hardware	1.0	1.2	2.1	2.0	6.3
Gateware	2.4	1.7	1.9	0.6	6.6
Software for tests	1.2	1.1	0.4	0.2	2.9
Timing distribution techniques	2.5	2.5	1.0	1.0	7.0
Total (FTE)	7.9	6.8	5.6	4.1	24.5

The comparison between required and available FTE shows that the project in unserstaffed by 20 %. The shortfall is mainly in the *time distribution techniques* and *exploratory features*

Required person-power for the Upgrade II version:

The person-power will depend on the option chosen. It will require the same commitment, $\mathcal{O}(6)$ FTE per year, if the Upgrade II version is similar in complexity to the PCIe400.

Costs of PCIe400 and Upgrade II developements

- The production of the boards is funded by the subdetector projects.
- IN2P3 will fund the pre-production boards and the tooling required for the qualification and burning tests of the boards at the manufacturer.

Item	Run	3	LS3			Run 4				LS4		Total
item	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	
Test bench	10											10
Study liquid cooling		16										16
Production tools at EMS	20	35										55
PCIe400 production pre-series		150										150
Development kits	16	8	2									26
Prototypes Upgrade II version				10	300							310
Production tools at EMS						60						60
Upgrade II production pre-series							240					240
Total per year	46	209	2	10	300	60	240					867

Projection per version:

LS3	231 k€
LS4	636 k€
Total	867 k€

Risks

Retirement of the Scientific Coordinator

Additional resources made available by CPPM or project taken on by someone from another participating institutes.

Departure of a project member with a key skill.

Follow up on the recruitment strategies in the light of the identified competences with the participating institutes and IN2P3 management

Reduction in workforce due to non-extension of fixed-term contracts or nonappointment of permanent staff

Reallocation of tasks to other members of the project team or identification of a new member of staff through networks.

No phase determinism for Agilex transceivers

The PCIe40 might be a backup solution for Run 4. Another approach is to use competitor board for the time distribution

Non-functional PCIe400 prototype

Reorganizing the schedule to bring forward the revision phase

Delays in development and qualification due to technical difficulties

No more duplication of prototype boards. PCIe Gen5 servers will be qualified using the four prototype boards, while RICH sub-detector developers will use the PCIe40 board

Conclusions

- The proposed project is a continuation of our contributions over more than 25 years, in particular the level-0 muon processor and the multipurpose card, pcie40.
- The IN2P3 is supporting a flagship development in electronics through the R&D of the PCIe400 card (2022 - 2025). The LHCC recognises its importance by approving the LHCb Data Acquisition Enhancement TDR.
- The PCIe400 card is a key component of the LHCb experiment. The collaboration has recognised its importance by creating a sub-project in the Online and by appointing a deputy in charge of the backend for the Upgrade II.
- The project is supported by 5 institutes of IN2P3 and the LHCb Online group. The participating institutes are encouraged to increase their contribution to this large project.
- The PCIe400 is the cornerstone of keeping pace with technology and preparing for the final version of the multipurpose card, which is expected to be specified in 2027.
- Finally, we believe that our major contributions will improve the physics output in the flavour and heavy ion sectors and open the doors to new ideas that can be exploited by future experiments.

Backup...

The RICH time gate...



[LHCb-TDR-024]

	Sensor $[\sigma]$	ASIC time walk	FE time gate	TDC time bin
LHC Run 3	$150 \mathrm{\ ps}$	$< 4\mathrm{ns}$	$6.25 \ \mathrm{ns}$	None
LHC Run 4	$150 \mathrm{\ ps}$	CFD correction	$2\mathrm{ns}$	$25\mathrm{ps}$
HL-LHC Run 5	$\sim 50\mathrm{ps}$	CFD correction	$150-300~\mathrm{ps}$	$25\mathrm{ps}$



Figure 28: Kaon efficiency for 1% pion misidentification versus momentum, for the Run 3 and the three RICH Upgrade II options at different luminosities, for (left) 300 ps and (right) 150 ps time windows, assuming the same average photoelectron yields.

Safety margin planning LS3



Safety margin ~12 months :

- Revision of 12 months is for of full redesign of the card Minor revision can be done in about 3 to 6 months
- Production of 150 unit should not exceed 3 months.
 It mainly depends on the contract signed with the EMS
- In case of disaster the PCIe40 is the backup

Safety margin planning LS4

	Run	3			LS3	Run 4						LS4		
	2025	202	26	2027	2028	2029	2030	2031	20	2032		33	2034	2035
Upgrade II				Spec.	Design		Debug & Qualif.	Production Preparation		Prod.		Sub Com	-detector missioning	

Safety margin ?

- Depend on the complexity of the design and on the delivery date
- The PCIe400 took a long time to specify and design because both the FPGA and the card were in development at the same time. For the Upgrade II version, we hope to use a well-known FPGA that is already in production. This will reduce the specification and design steps by a year
- Adapting the project to ensure that it is delivered safely and on time
- In case of disaster, the PCIe400 could be the backup.

Possible concentrator for Run 5...



Figure 19: First sketch of a concentrator board upstream to the PCIe400 board.

Simplified view of the TFC – Run 3



Event Builder: Traffic scheduling



- The processing of **N** events is divided into **N** phases (**N** is the number of EB nodes
- In every phase one RU sends data to one BU, and every BU receives data from one RU
- During phase **n** RU **x** sends data to BU (**x** + **n**)%**N**
- All the units switch synchronously from phase **n** to phase **n** + 1

Congestion-free traffic on "selected networks" (e.g. fat-tree networks)

F. Pisani

LHCb Event Building system in Run3

Retina architecture



Step 3: Find the local maxima and compute centroid



Figure 18: Track reconstruction steps with the Retina architecture.

DWT processor – Run 4



Figure 28: Connection scheme of the DWT processor.



Figure 24: Possible data flow in Upgrade II.

Evolution of switch bandwidth

